

FMUN5111DW-Q1 Thru FMUN5135DW-Q1

List

List.....	1
Package outline.....	2
Features.....	2
Mechanical data.....	2
Maximum ratings	2
Electrical characteristics.....	2~3
Rating and characteristic curves.....	4
Pinning information.....	5
Device marking, Resistor values and ordering information	5
Suggested solder pad layout.....	5
Package Information.....	6
Reel packing.....	7
Suggested thermal profiles for soldering processes.....	7

FMUN5111DW-Q1 Thru FMUN5135DW-Q1

PNP Silicon Surface Mount Transistors with Monolithic Bias Resistor Network

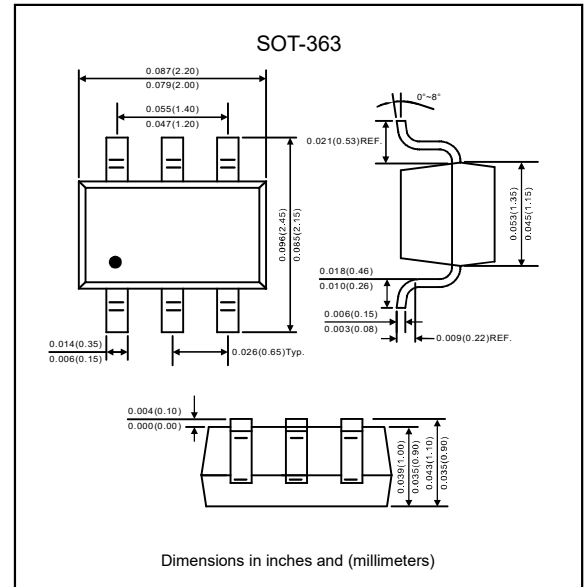
Features

- Simplifies circuit design.
- Reduces Board Space.
- Reduces Component Count.
- We declare that the material of product compliance with RoHs require.
- -Q1 for automotive and other applications requiring unique site and control change requirements; AEC-Q101 qualified and PPAP capable.
- Suffix "-H" indicates Halogen free parts, ex. FMUN5211DW-Q1-H.

Mechanical data

- Epoxy: UL94-V0 rated flame retardant
- Case : Molded plastic, SOT-363
- Terminals : Solder plated, solderable per MIL-STD-750, Method 2026
- Mounting Position : Any

Package outline

Maximum ratings (At $T_A=25^\circ\text{C}$ unless otherwise noted, Common for Q₁ and Q₂)

Parameter	Symbol	Value	Unit
Collector base voltage	$-V_{CBO}$	50	V
Collector to emitter voltage	$-V_{CEO}$	50	V
Collector current	$-I_C$	100	mA
Power dissipation (Note1)	P_D	200	mW
Junction temperature	T_J	150	$^\circ\text{C}$
Storage temperature range	T_{stg}	-55 to +150	$^\circ\text{C}$
Thermal resistance junction to ambient (Note 1)	$R_{\theta JA}$	493	$^\circ\text{C/W}$
Thermal resistance junction to lead (Note 1)	$R_{\theta JL}$	188	$^\circ\text{C/W}$

Note : 1. FR-4 @Minimum pad

Electrical characteristics ($T_A=25^\circ\text{C}$ unless otherwise noted, common for Q1 and Q2)(Continued)

Parameter	Conditions	Symbol	Device	Min.	Typ.	Max.	Unit
DC Current gain	$-V_{CE} = 10\text{V}, -I_C = 5\text{mA}$	h_{FE}	FMUN5111DW-Q1	35	60	250	
			FMUN5112DW-Q1	60	100		
			FMUN5113DW-Q1	80	140		
			FMUN5114DW-Q1	80	140		
			FMUN5115DW-Q1	160	250		
			FMUN5116DW-Q1	160	250		
			FMUN5130DW-Q1	3	5		
			FMUN5131DW-Q1	8	15		
			FMUN5132DW-Q1	15	27		
			FMUN5133DW-Q1	80	140		
			FMUN5134DW-Q1	80	130		
			FMUN5135DW-Q1	80	140		

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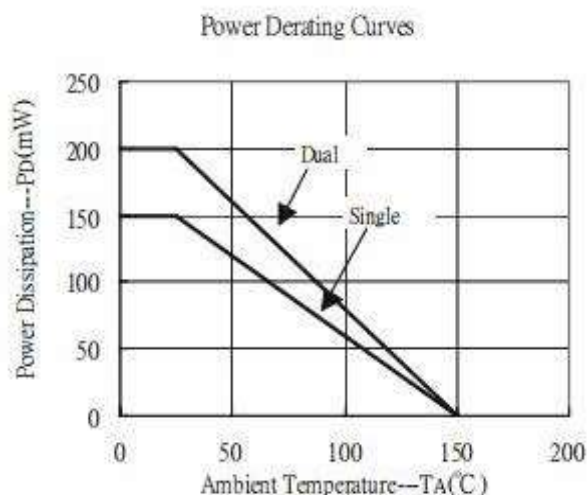
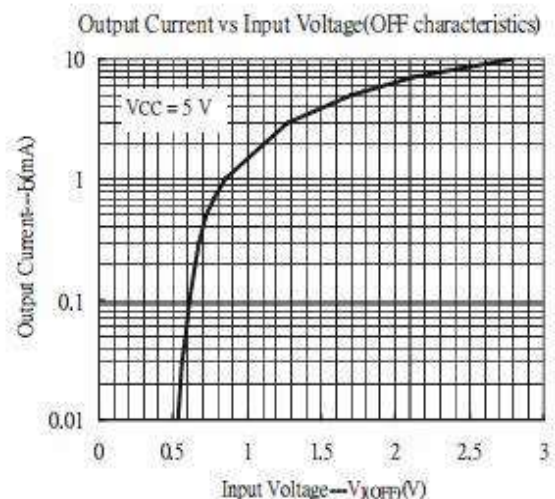
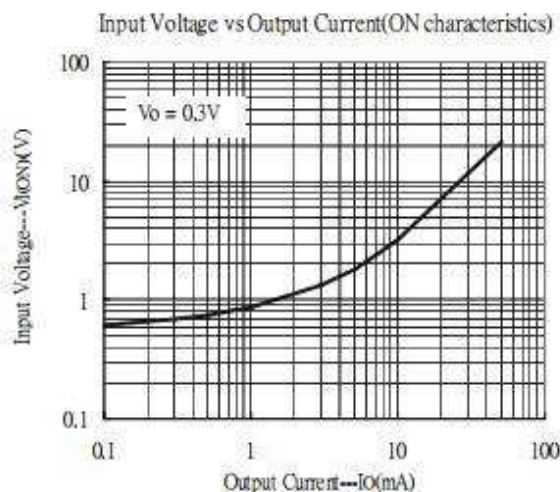
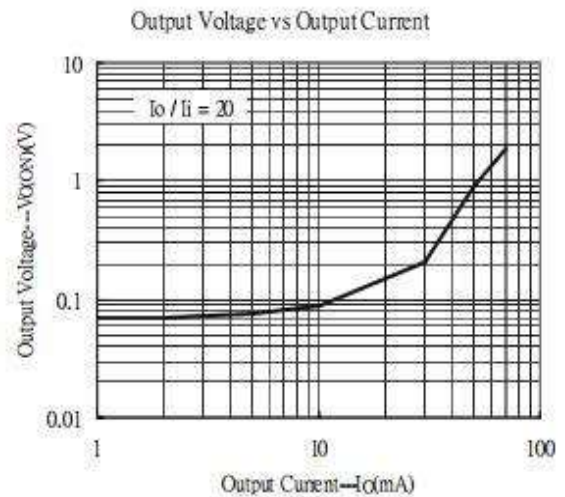
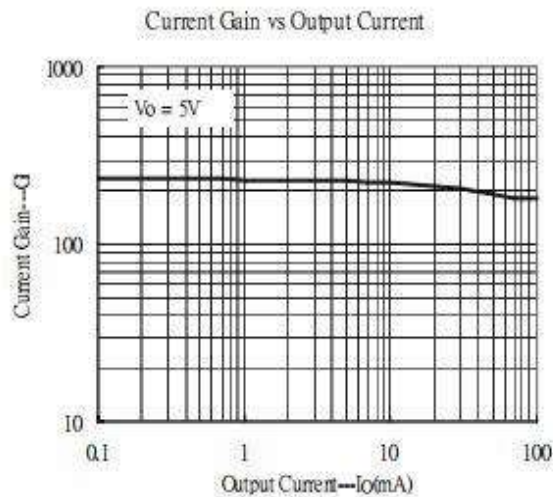
Electrical characteristics (At $T_A=25^{\circ}\text{C}$ unless otherwise noted, Common for Q₁ and Q₂) (Continued)

Parameter	Conditions	Device	Symbol	Min.	Typ.	Max.	Unit
Collector base breakdown voltage	$-I_C=10\mu\text{A}$, $I_E=0$		$-V_{(BR)CBO}$	50			V
Collector emitter breakdown voltage	$-I_C=2\text{mA}$, $I_B=0$		$-V_{(BR)CEO}$	50			V
Collector base cut off current	$-V_{CB}=50\text{V}$, $I_E=0$		$-I_{CBO}$			100	nA
Collector emitter cut off current	$-V_{CE}=50\text{V}$, $I_B=0$		$-I_{CEO}$			500	nA
Emitter base cut off current	$-V_{EB}=6\text{V}$	FMUN5111DW-Q1	$-I_{EBO}$			0.5	mA
		FMUN5112DW-Q1				0.2	
		FMUN5113DW-Q1				0.1	
		FMUN5114DW-Q1				0.2	
		FMUN5115DW-Q1				0.9	
		FMUN5116DW-Q1				1.9	
		FMUN5130DW-Q1				4.3	
		FMUN5131DW-Q1				2.3	
		FMUN5132DW-Q1				1.5	
		FMUN5133DW-Q1				0.18	
		FMUN5134DW-Q1				0.13	
		FMUN5135DW-Q1				0.2	
Collector emitter saturation voltage	$-I_C=10\text{mA}$, $-I_B=0.3\text{mA}$		$-V_{CE(sat)}$				V
	$-I_C=10\text{mA}$, $-I_B=5\text{mA}$	FMUN5130DW-Q1				0.25	
		FMUN5131DW-Q1					
	$-I_C=10\text{mA}$, $-I_B=1\text{mA}$	FMUN5132DW-Q1					
		FMUN5134DW-Q1					
Output voltage (on)	$-V_{CC}=5\text{V}$, $-V_B=2.5\text{V}$, $R_L=1\text{K}\Omega$		$-V_{OL}$			0.2	V
	$-V_{CC}=5\text{V}$, $-V_B=3.5\text{V}$, $R_L=1\text{K}\Omega$	FMUN5213DW-Q1					
Output voltage (off)	$-V_{CC}=5\text{V}$, $-V_B=0.5\text{V}$, $R_L=1\text{K}\Omega$		$-V_{OH}$	4.9			V
	$-V_{CC}=5\text{V}$, $-V_B=0.05\text{V}$, $R_L=1\text{K}\Omega$	FMUN5230DW-Q1					
	$-V_{CC}=5\text{V}$, $-V_B=0.25\text{V}$, $R_L=1\text{K}\Omega$	FMUN5115DW-Q1					
		FMUN5116DW-Q1					
		FMUN5231DW-Q1					
		FMUN5232DW-Q1					

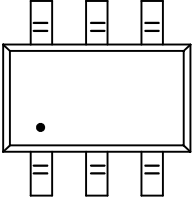
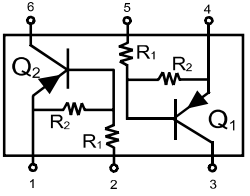
Note : Pulse Test : Pulse Width < 300 μs , Duty Cycle < 2.0%

FMUN5111DW-Q1 Thru FMUN5135DW-Q1

Rating and characteristic curves

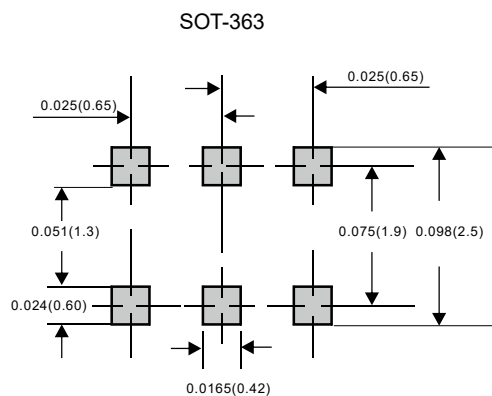


FMUN5111DW-Q1 Thru FMUN5135DW-Q1**Pinning information**

Pin	Simplified outline	Symbol
Pin2, 5 Base Pin1, 4 Emitter Pin3, 6 Collector		

Device marking, Resistor values and ordering information

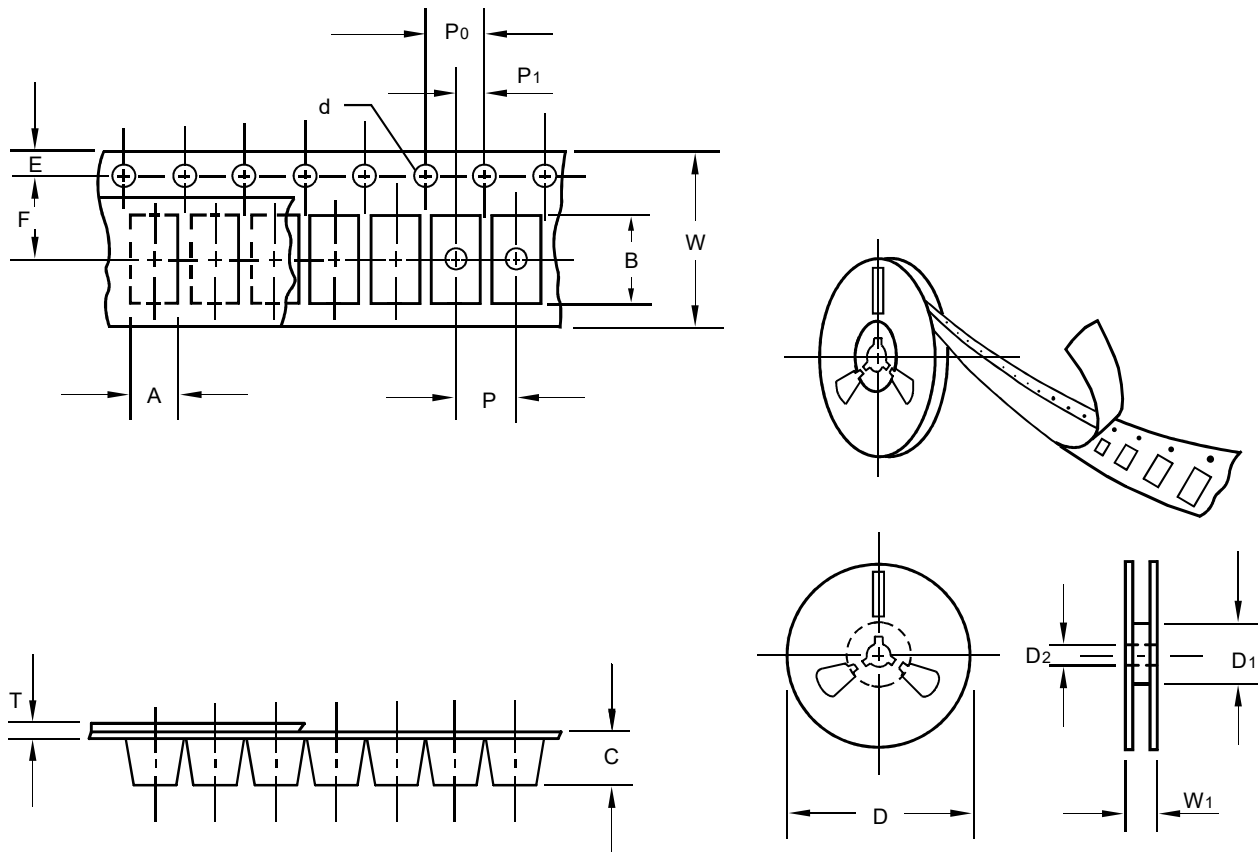
Device	Marking	Input resistor R_1 (K Ω)			R_2 (K Ω)	Resistor ratio R_1 / R_2		
		Min	Normal	Max		Min	Normal	Max
FMUN5111DW-Q1	0A	7	10	13	10	0.8	1.0	1.2
FMUN5112DW-Q1	0B	15.4	22	28.6	22	0.8	1.0	1.2
FMUN5113DW-Q1	0C	32.9	47	61.1	47	0.8	1.0	1.2
FMUN5114DW-Q1	0D	7	10	13	47	0.17	0.21	0.25
FMUN5115DW-Q1	0E	7	10	13	—	—	—	—
FMUN5116DW-Q1	0F	3.3	4.7	6.1	—	—	—	—
FMUN5130DW-Q1	0G	0.7	1	1.3	1	0.8	1.0	1.2
FMUN5131DW-Q1	0H	1.5	2.2	2.9	2.2	0.8	1.0	1.2
FMUN5132DW-Q1	0J	3.3	4.7	6.1	4.7	0.8	1.0	1.2
FMUN5133DW-Q1	0K	3.3	4.7	6.1	47	0.055	0.1	0.185
FMUN5134DW-Q1	0L	15.4	22	28.6	47	0.38	0.47	0.56
FMUN5135DW-Q1	0M	1.54	2.2	2.86	47	0.038	0.047	0.056

Suggested solder pad layout

Dimensions in inches and (millimeters)

FMUN5111DW-Q1 Thru FMUN5135DW-Q1

Packing information



unit:mm

Item	Symbol	Tolerance	SOT-363
Carrier width	A	0.1	2.36
Carrier length	B	0.1	2.40
Carrier depth	C	0.1	1.20
Sprocket hole	d	0.1	1.50
13" Reel outside diameter	D	2.0	-
13" Reel inner diameter	D ₁	min	-
7" Reel outside diameter	D	2.0	178.00
7" Reel inner diameter	D ₁	min	62.00
Feed hole diameter	D ₂	0.5	13.00
Sprocket hole position	E	0.1	1.75
Punch hole position	F	0.1	3.50
Punch hole pitch	P	0.1	4.00
Sprocket hole pitch	P ₀	0.1	4.00
Embossment center	P ₁	0.1	2.00
Overall tape thickness	T	0.1	0.23
Tape width	W	0.3	8.00
Reel width	W ₁	1.0	11.40

Note: Devices are packed in accordance with EIA standard RS-481-A and specifications listed above.

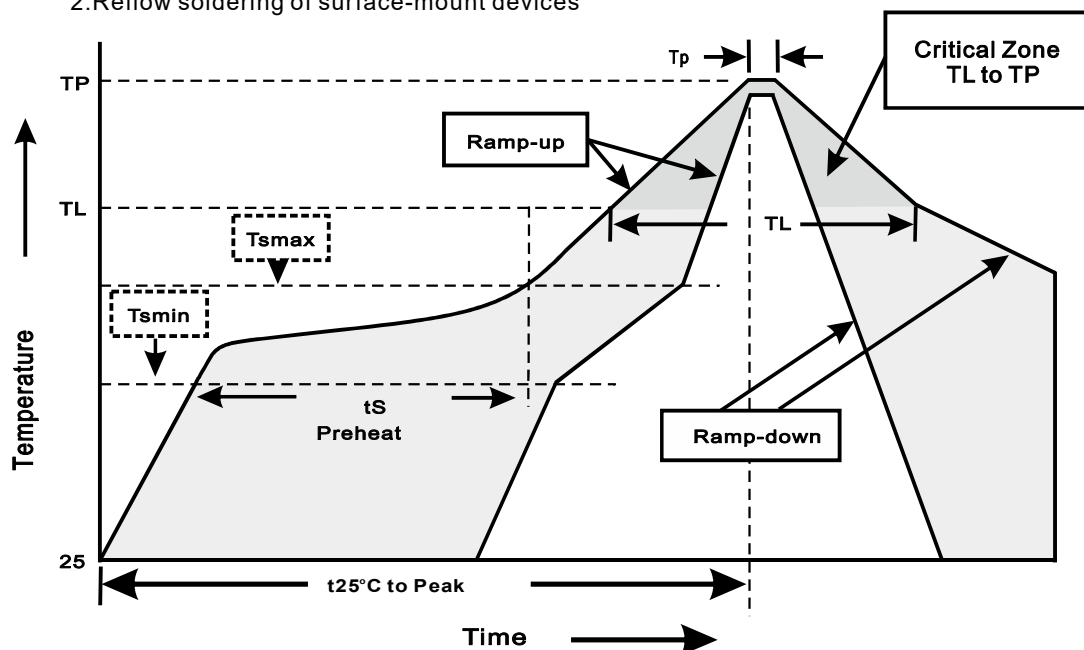
FMUN5111DW-Q1 Thru FMUN5135DW-Q1

Reel packing

PACKAGE	REEL SIZE	REEL (pcs)	COMPONENT SPACING (m/m)	BOX (pcs)	INNER BOX (m/m)	REEL DIA, (m/m)	CARTON SIZE (m/m)	CARTON (pcs)	APPROX. GROSS WEIGHT (kg)
SOT-363	7"	3,000	4.0	30,000	183*183*123	178	382*262*387	240,000	9.50

Suggested thermal profiles for soldering processes

- 1.Storage environment: Temperature=5°C~40°C Humidity=55%±25%
- 2.Reflow soldering of surface-mount devices



3.Reflow soldering

Profile Feature	Soldering Condition
Average ramp-up rate(T_L to T_P)	<3°C/sec
Preheat -Temperature Min(T_{smin}) -Temperature Max(T_{smax}) -Time(min to max)(t_s)	150°C 200°C 60~120sec
T_{smax} to T_L -Ramp-upRate	<3°C/sec
Time maintained above: -Temperature(T_L) -Time(t_L)	217°C 60~260sec
Peak Temperature(T_P)	255°C-0/+5°C
Time within 5°C of actual Peak Temperature(t_P)	10~30sec
Ramp-down Rate	<6°C/sec
Time 25°C to Peak Temperature	<6minutes